



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **L0110-04** DATE: 10/19/01
Product Affected: PA48 & PA56 (TSSOP) packages
of all Logic devices

Date Effective: **October 19, 2001**

MEANS OF DISTINGUISHING CHANGED DEVICES:

- Product Mark
- Back Mark
- Date Code
- Other

Contact: Bimla Paul

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Attachment: Yes No

Samples: N/A

DESCRIPTION AND PURPOSE OF CHANGE:

- Die Technology
- Wafer Fabrication Process To comply with the requirement of reflow temperature of +235°C +5/-0°C per IPC/JEDEC J-STD-020A. Moisture sensitivity level of all TSSOP 48 & 56 Logic devices will be changed from level 1 (Non-Moisture Sensitive) to level 3 (Moisture Sensitive)
- Assembly Process
- Equipment
- Material
- Testing
- Manufacturing Site Moisture sensitivity label per IPC/JEDEC J-STD-033 will be applied to the dry pack. effective 10/19/2001 (See attachment # 1).
- Data Sheet
- Other

RELIABILITY/QUALIFICATION SUMMARY:

Moisture sensitivity level is changed from level 1 to level 3.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____

Approval for shipments prior to effective date.

Name/Date: _____

E-Mail Address: _____

Title: _____

Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____

DATE: _____




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ATTACHMENT # 1 - PCN #: L0110-04

Moisture Sensitivity Label for level 3

	CAUTION This Bag Contains MOISTURE- SENSITIVE DEVICES	LEVEL 3 If Blank, see adjacent bar code label
<ol style="list-style-type: none">1. Calculated shelf life in sealed bag: 12 months at $< 40^{\circ}\text{C}$ and $< 90\%$ relative humidity (RH)2. Peak package body temperature: <input type="checkbox"/> 225°C <input type="checkbox"/> 240°C3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must<ol style="list-style-type: none">a) Mounted within 168 hours of factory conditions $\leq 30^{\circ}\text{C}/60\%$b) Stored at $\leq 10\%$ RH4. Devices require bake, before mounting, if:<ol style="list-style-type: none">a) Humidity Indicator Card is $>10\%$ when read at $23 \pm 5^{\circ}\text{C}$,b) 3a or 3b is not met.5. If baking is required, devices may be baked for 48 hours at $125 \pm 5^{\circ}\text{C}$		
<p>Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure</p>		
Bag Seal Date : _____		
If Blank, see adjacent bar code label		
Note: Level and body temperature defined by IPC/JEDEC J-STD-020		